

2SK2937

Silicon N Channel MOS FET
High Speed Power Switching

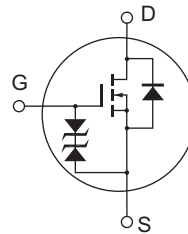
REJ03G1051-0500
(Previous: ADE-208-560C)
Rev.5.00
Sep 07, 2005

Features

- Low on-resistance
 $R_{DS} = 0.026 \Omega$ typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source

Outline

RENESAS Package code: PRSS0003AD-A
(Package name: TO-220FM)



1. Gate
2. Drain
3. Source

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	25	A
Drain peak current	I _{D(pulse)} ^{Note1}	100	A
Body-drain diode reverse drain current	I _{DR}	25	A
Avalanche current	I _{AP} ^{Note3}	20	A
Avalanche energy	E _{AR} ^{Note3}	34	mJ
Channel dissipation	P _{ch} ^{Note2}	25	W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Notes: 1. PW ≤ 10μs, duty cycle ≤ 1 %
 2. Value at T_c = 25°C
 3. Value at T_{ch} = 25°C, R_g ≥ 50 Ω

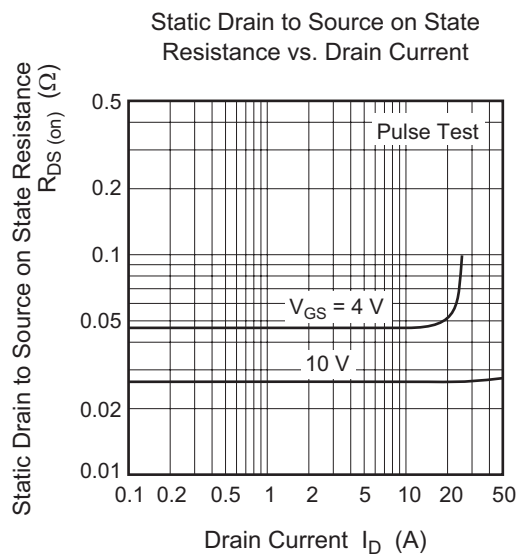
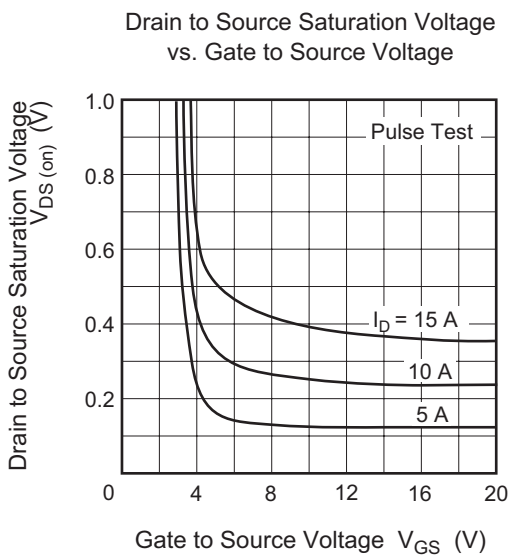
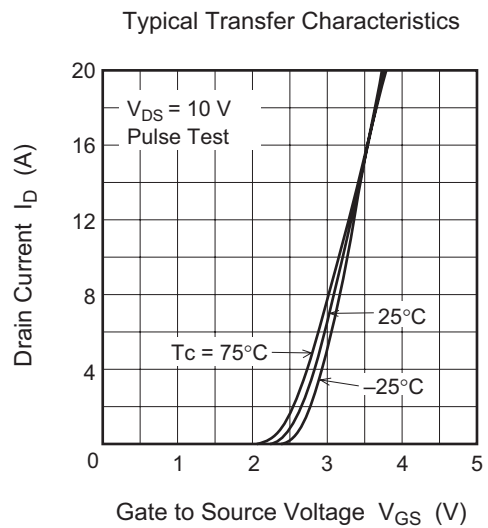
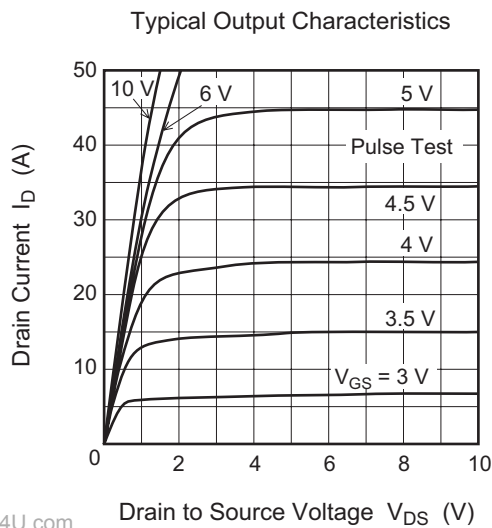
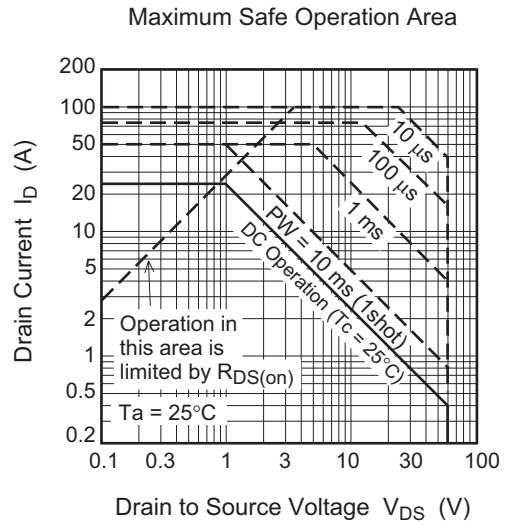
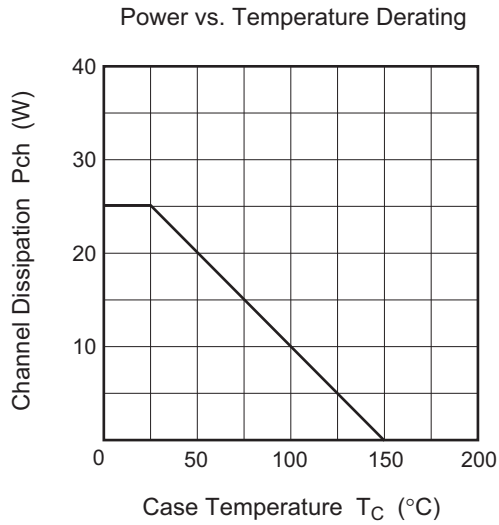
Electrical Characteristics

(Ta = 25°C)

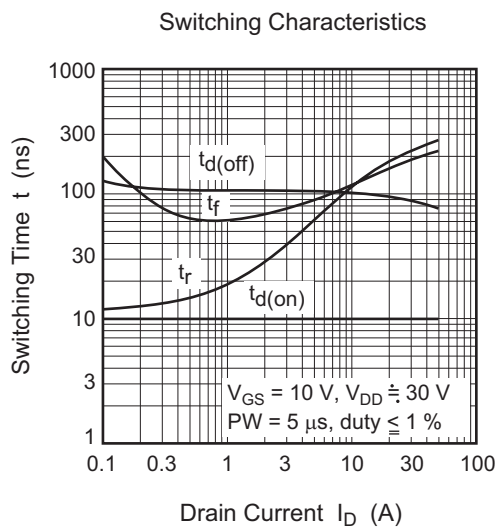
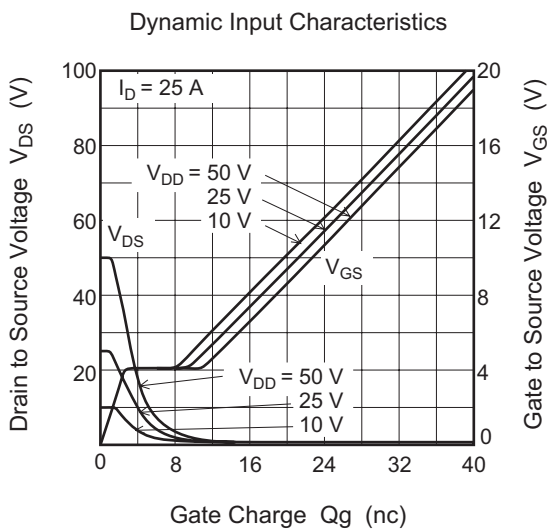
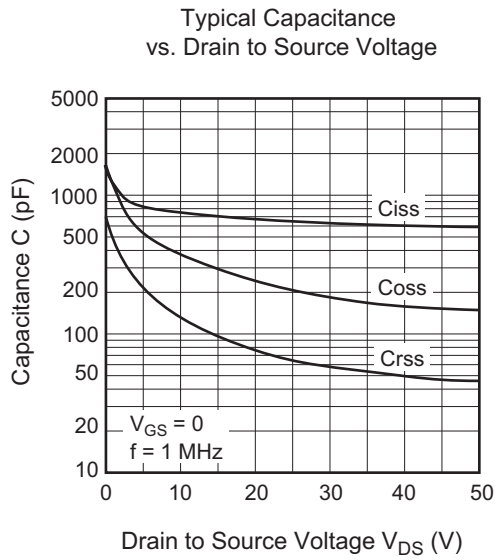
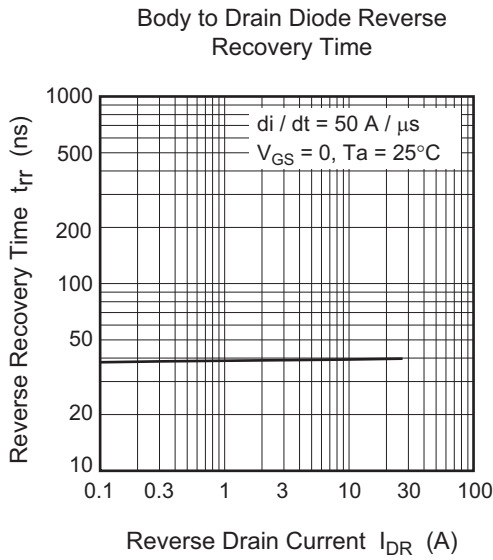
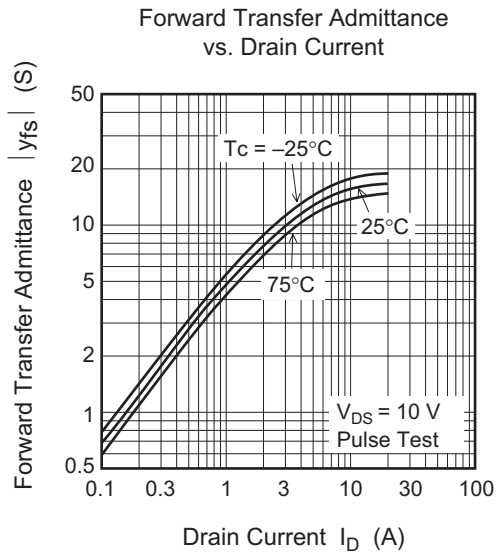
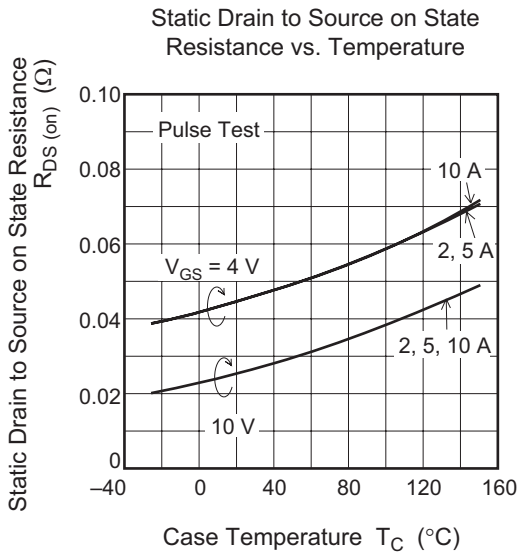
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	60	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	±20	—	—	V	I _G = ±100 μA, V _{DS} = 0
Gate to source leak current	I _{GSS}	—	—	±10	μA	V _{GS} = ±16 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	10	μA	V _{DS} = 60 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	1.5	—	2.5	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state resistance	R _{DS(on)}	—	0.026	0.034	Ω	I _D = 15 A, V _{GS} = 10 V ^{Note4}
	R _{DS(on)}	—	0.045	0.070	Ω	I _D = 15 A, V _{GS} = 4 V ^{Note4}
Forward transfer admittance	y _{fs}	11	17	—	S	I _D = 15 A, V _{DS} = 10 V ^{Note4}
Input capacitance	C _{iss}	—	740	—	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz
Output capacitance	C _{oss}	—	380	—	pF	
Reverse transfer capacitance	C _{rss}	—	140	—	pF	
Turn-on delay time	t _{d(on)}	—	10	—	ns	
Rise time	t _r	—	160	—	ns	R _L = 2 Ω
Turn-off delay time	t _{d(off)}	—	100	—	ns	
Fall time	t _f	—	150	—	ns	
Body-drain diode forward voltage	V _{DF}	—	0.95	—	V	I _F = 25A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	—	40	—	ns	I _F = 25A, V _{GS} = 0 di _F / dt = 50 A/μs

Note: 4. Pulse test

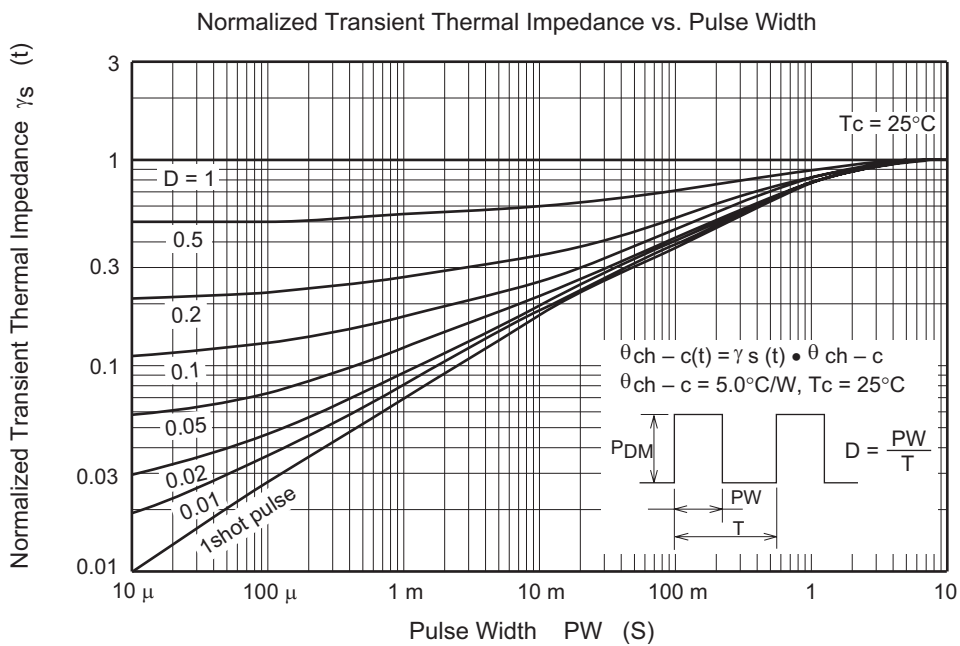
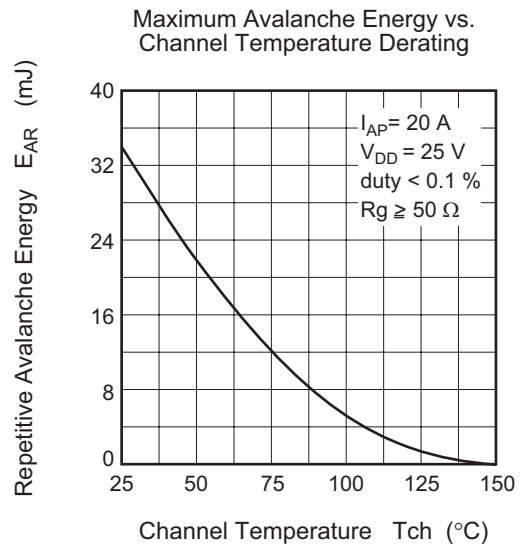
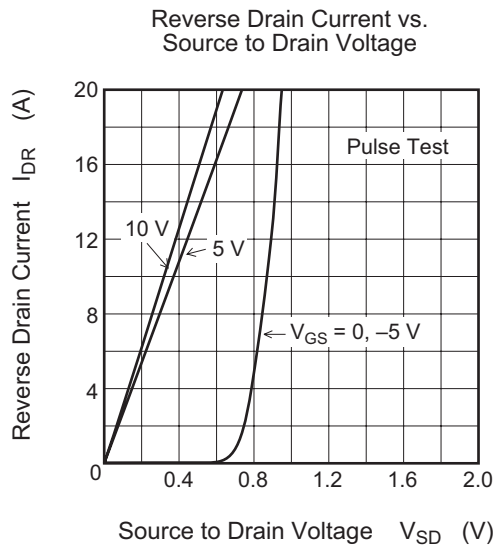
Main Characteristics



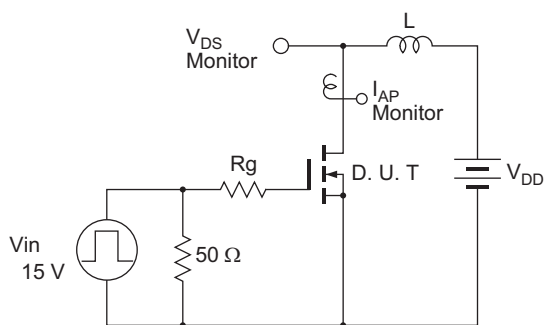
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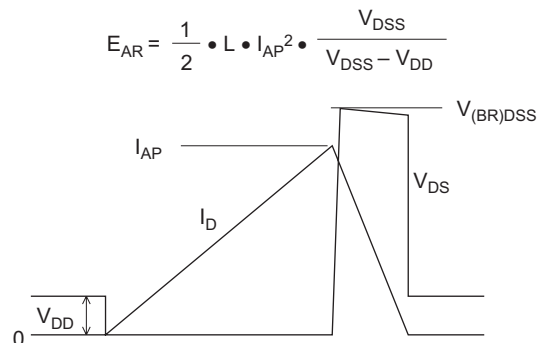
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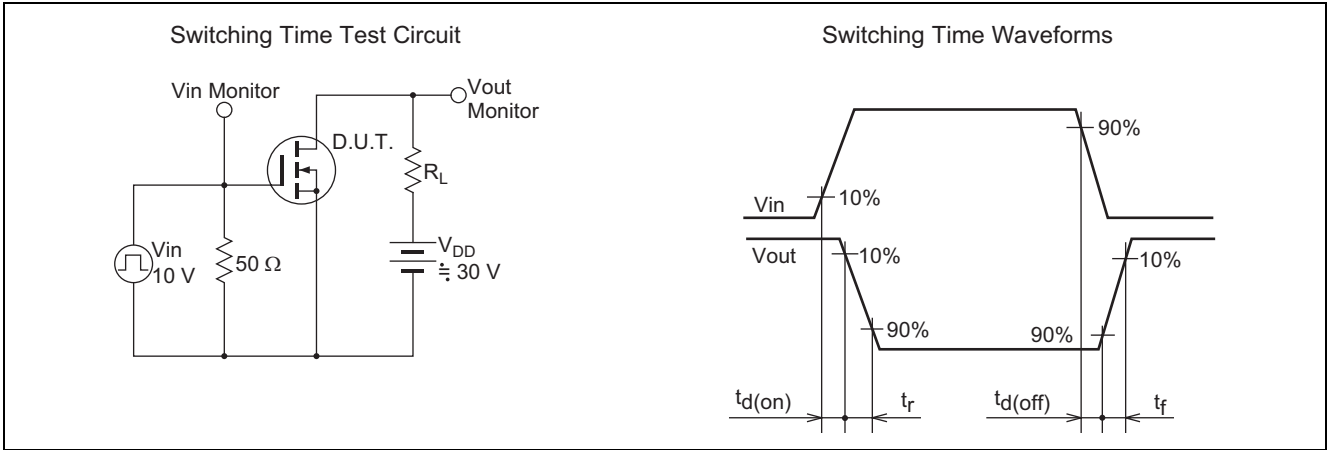


Avalanche Test Circuit

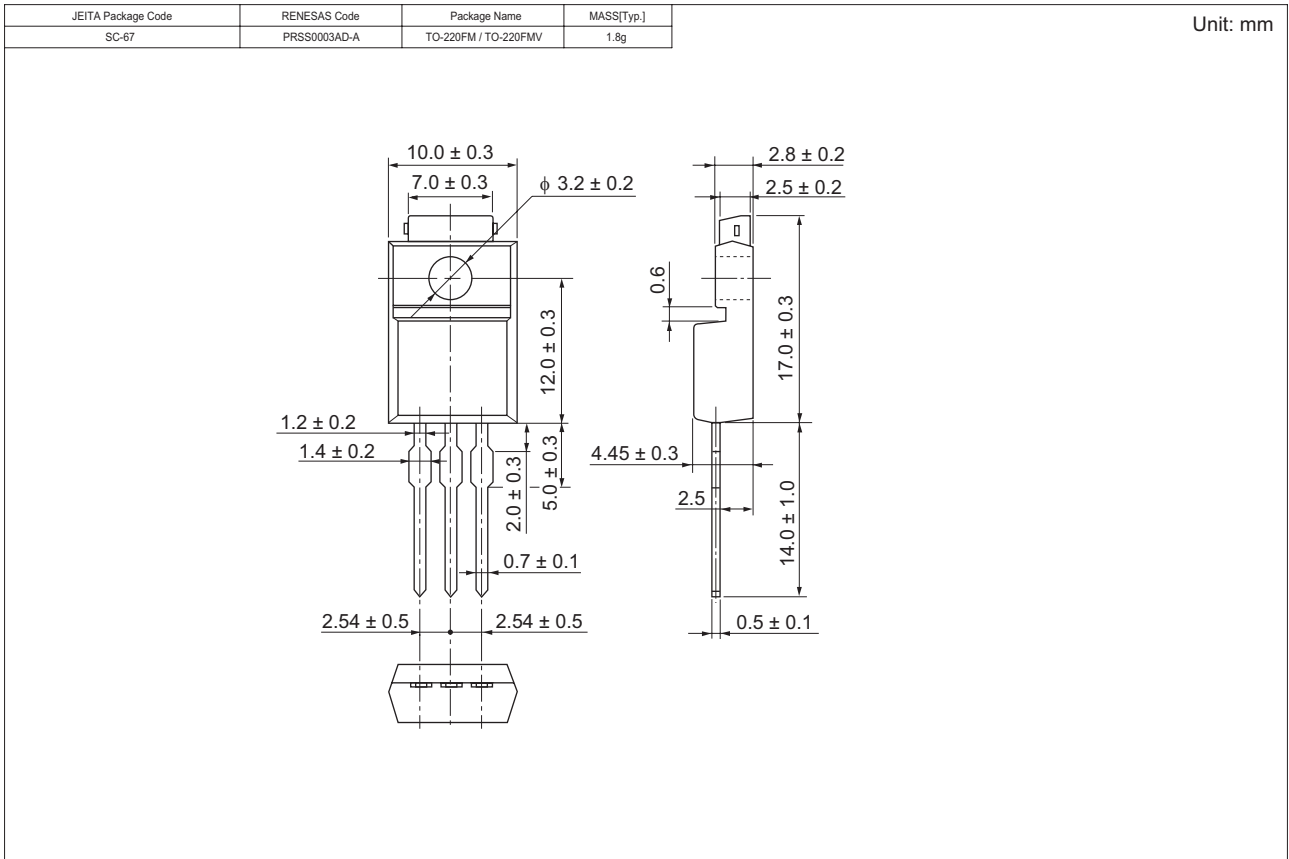


Avalanche Waveform





Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2937-E	500 pcs	Box (Sack)

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Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd.

Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510